DZ2U068

Silicon epitaxial planar type

For constant voltage
For surge absorption circuit
DZ27068 in USSMini2 type package

■ Features

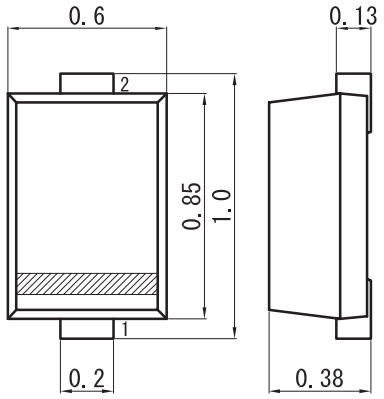
- Excellent rising characteristics of zener current I_Z
- Low zener operating resistance R_Z
- Halogen-free / RoHS compliant
  (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: G

■ Packaging

DZ2U06800L Embossed type (Thermo-compression sealing): 10000 pcs / reel (standard)

Unit: mm



1: Cathode
2: Anode

Panasonic	USSMini2-F2-B
JEITA	SC-116A
Code	SOD-923

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	I_{FRM}	200	mA
Total power dissipation *1	P_T	120	mW
Electrostatic discharge *2	ESD	±15	kV
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	–55 to +150	°C

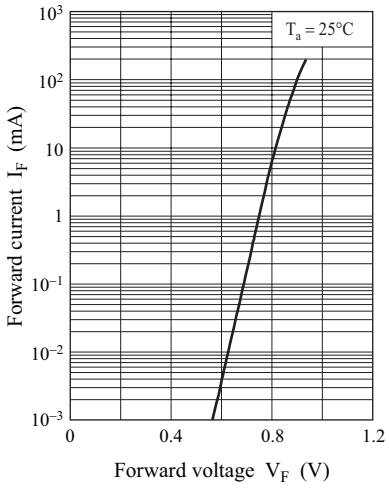
Note) ∗1: Mounted on glass epoxy print board. (45 mm × 45 mm × 1 mm)
Solder in (Recommended land pattern)
∗2: Test method:IEC61000-4-2 (C = 150 pF, R = 330 Ω, Contact discharge:10 times)

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

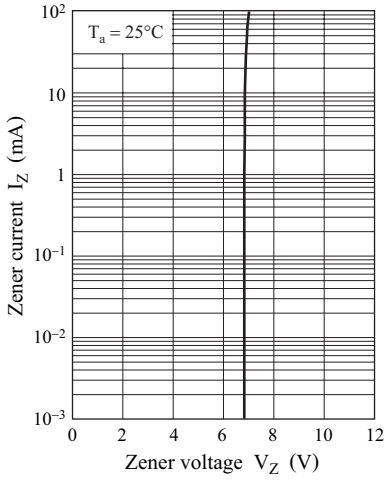
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 10$ mA			1.0	V
Zener voltage *1, 2	V_Z	$I_Z = 5$ mA	6.46		7.14	V
Zener operating resistance	R_Z	$I_Z = 5$ mA			20	Ω
Reverse current	I_R	$V_R = 4.0$ V			0.1	μA
Temperature coefficient of zener voltage *3	S_Z	$I_Z = 5$ mA		3.2		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 5 MHz.
3. ∗1: The temperature must be controlled 25°C for V_Z measurement. V_Z value measured at other temperature must be adjusted to V_Z (25°C)
∗2: V_Z guaranteed 20 ms after current flow.
∗3: T_j = 25°C to 150°C

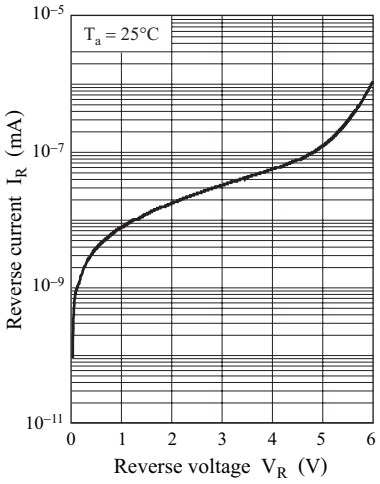
I_F — V_F



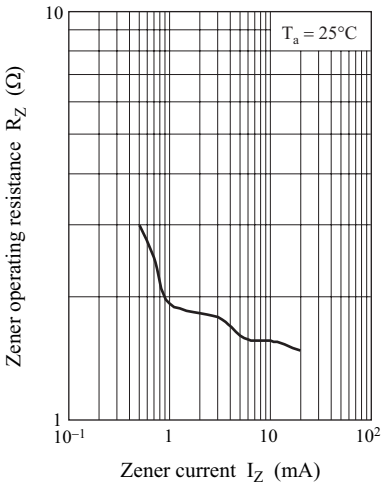
I_Z — V_Z



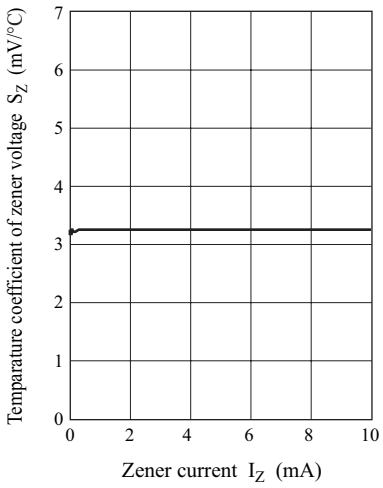
I_R — V_R



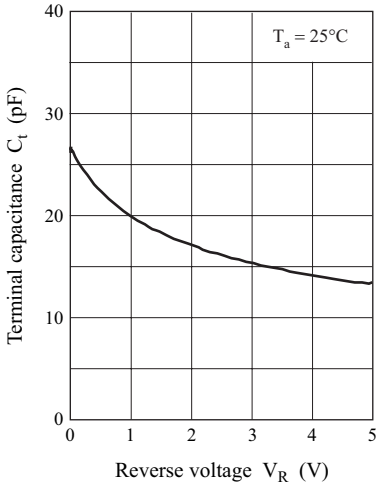
R_Z — I_Z



S_Z — I_Z

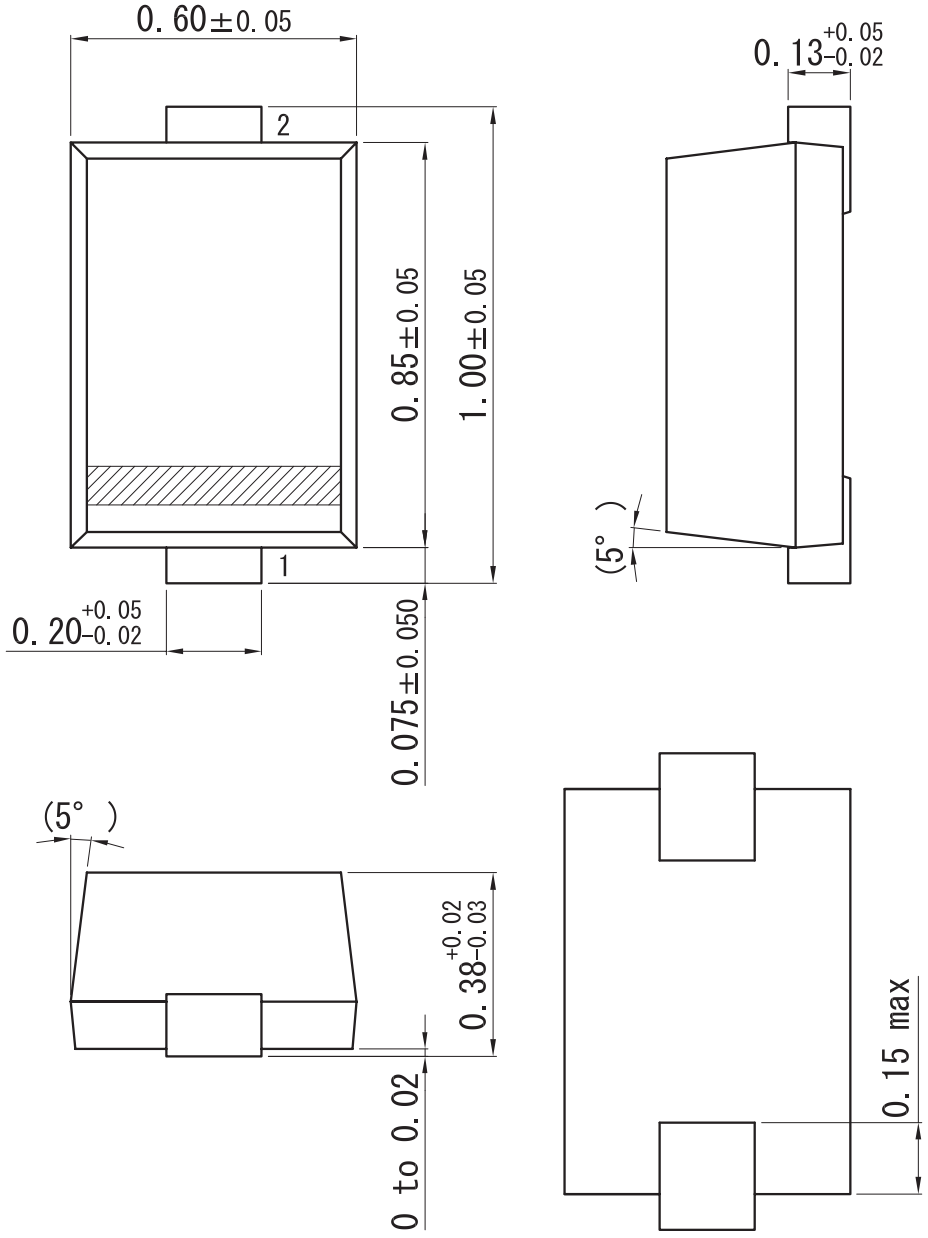


C_t — V_R

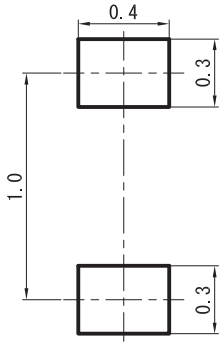


USSMini2-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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